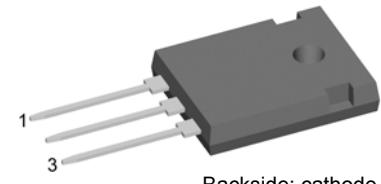
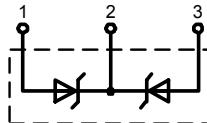


preliminary

**Schottky**

High Performance Schottky Diode  
 Low Loss and Soft Recovery  
 Common Cathode

 **$V_{RRM} = 200 \text{ V}$**  **$I_{FAV} = 2 \times 45 \text{ A}$**  **$V_F = 0.86 \text{ V}$** **Part number****DSA 90 C 200HB****Features / Advantages:**

- Very low  $V_F$
- Extremely low switching losses
- Low  $I_{rm}$ -values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

**Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

**Package:**

TO-247AD

- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

**Ratings**

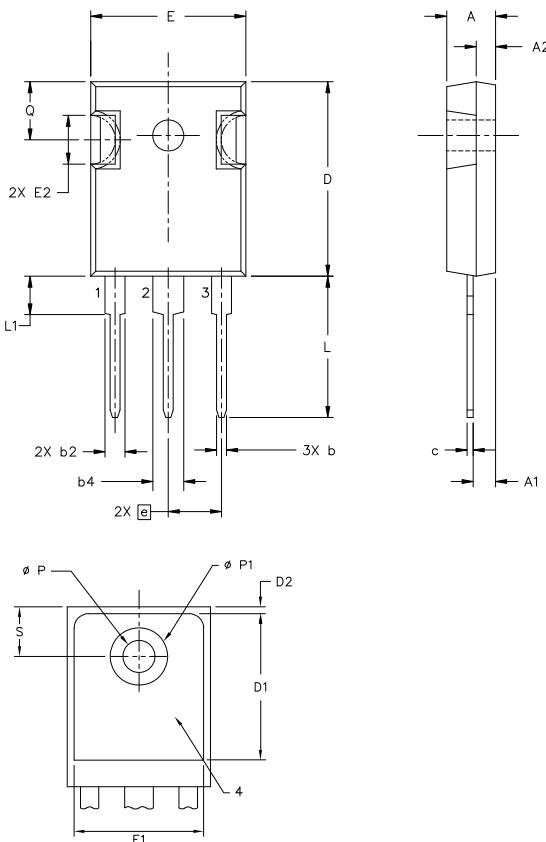
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^\circ\text{C}$			200	V
$I_R$	reverse current	$V_R = 200 \text{ V}$ $V_R = 200 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1.8 5	mA
$V_F$	forward voltage	$I_F = 45 \text{ A}$ $I_F = 90 \text{ A}$ $I_F = 45 \text{ A}$ $I_F = 90 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		0.96 1.18 0.86 1.14	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$	$T_c = 150^\circ\text{C}$		45	A
$V_{FO}$ $r_F$	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ\text{C}$		0.52 6.5	V $\text{m}\Omega$
$R_{thJC}$	thermal resistance junction to case				0.55	K/W
$T_{VJ}$	virtual junction temperature		-55		175	°C
$P_{tot}$	total power dissipation	$T_c = 25^\circ\text{C}$			275	W
$I_{FSM}$	max. forward surge current	$t_p = 10 \text{ ms}$ (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$		450	A
$C_J$	junction capacitance	$V_R = 100 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ\text{C}$		115	pF
$E_{AS}$	non-repetitive avalanche energy	$I_{AS} = \text{tbd A}; L = 100 \mu\text{H}$	$T_{VJ} = 25^\circ\text{C}$		tbd	mJ
$I_{AR}$	repetitive avalanche current	$V_A = 1.5 \cdot V_R$ typ.; $f = 10 \text{ kHz}$			tbd	A

Ratings						
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per pin*			70	A
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W
$M_D$	mounting torque		0.8		1.2	Nm
$F_C$	mounting force with clip		20		120	N
$T_{stg}$	storage temperature		-55		150	°C
Weight				6		g

\*  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines TO-247AD



Symbol	Inches		Millimeters	
	min	max	min	max
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.215 BSC		5.46 BSC	
L	0.780	0.800	19.80	20.30
L1	-	0.177	-	4.49
ØP	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	0.242 BSC		6.14 BSC	
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
ØP1	-	0.291	-	7.39

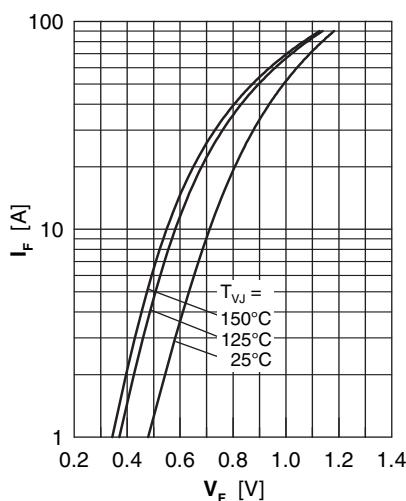


Fig. 1 Maximum forward voltage drop characteristics

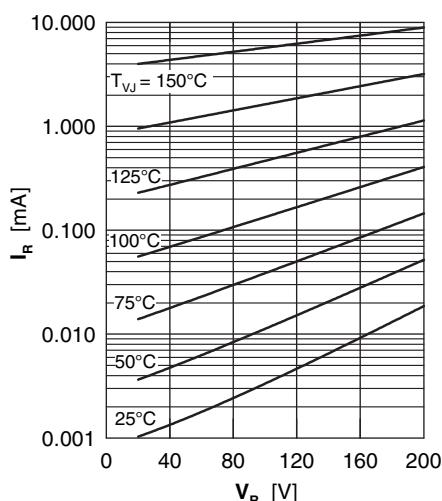


Fig. 2 Typ. reverse current  $I_R$  versus reverse voltage  $V_R$

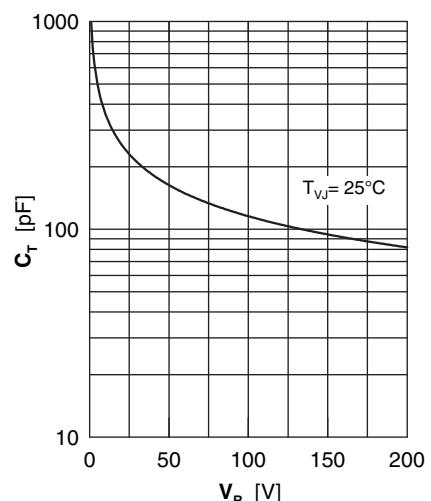


Fig. 3 Typ. junction capacitance  $C_T$  versus reverse voltage  $V_R$

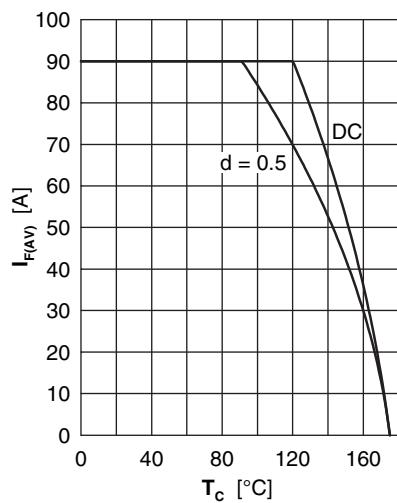


Fig. 4 Avg: forward current  $I_{F(AV)}$  versus case temperature  $T_C$

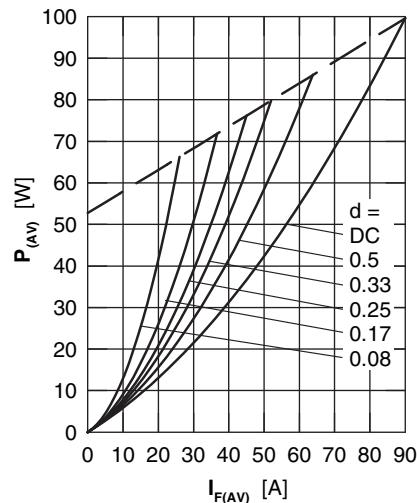


Fig. 5 Forward power loss characteristics

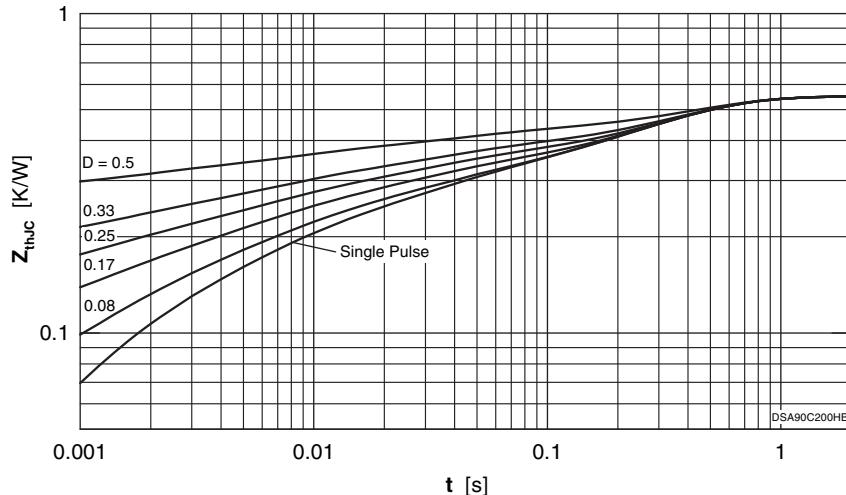


Fig. 6 Transient thermal impedance junction to case at various duty cycles